WHAT IS CLAIMED IS:

1. A printed circuit board unit comprising:

a printed circuit board;

an electronic component;

a solder bump interposed between the printed circuit board and the electronic component so as to fix the electronic component to the printed circuit board; and

an insulated film disposed between the printed circuit board and the electronic component so as to define a through hole for receiving the solder bump.

2. The printed circuit board unit according to claim 1, wherein the through hole is designed to form a constriction in the solder bump between the printed circuit board and the electronic component.

3. The printed circuit board unit according to claim 2, wherein the insulated film is superposed on the printed circuit board so as to form the constriction right on a conductive pad on the printed circuit board.

4. The printed circuit board unit according to claim 3, wherein the conductive pad comprises a base conductive layer on a substrate of the printed circuit board, and a surface conductive layer having a corrosion resistance higher than the base conductive layer and superposed on a top surface of the base conductive layer.

5. The printed circuit board unit according to claim 4, wherein the base conductive layer is a copper layer.

6. The printed circuit board unit according to claim 5, wherein the surface conductive layer is a nickel layer.

7. The printed circuit board unit according to claim 1, wherein an outer peripheral size of the solder bump is set smaller than an inner peripheral size of the through hole.

Sub B2

8. The printed circuit board unit according to claim 7, wherein an inner surface of the through hole is covered with a coating wet to the solder bump.

9. The printed circuit board unit according to claim 7, wherein a thickness of the insulated film corresponds to a height of the solder bump on the printed circuit board.

10. A method of detaching an electronic component from a printed circuit board, comprising causing a relative movement between a conductive pad, disposed on the printed circuit board for receiving a solder bump under the electronic component, and a through hole defined in an insulated film for forming a constriction in the solder bump.

11. The method of detaching according to claim 10, wherein the insulated film is lifted up from the conductive pad on the printed circuit board.

12. The method of detaching according to claim 10, wherein the insulated film is driven to slide on the conductive pad when the solder bump is kept at a melting temperature.

13. A method of detaching an electronic component from

a printed circuit board, comprising:

keeping a solder bump at a melting temperature on a surface of a conductive pad on the printed circuit board under the electronic component; and

displacing a wall defined in an insulated film between the printed circuit board and the electronic component so as to surround the solder bumps.

14. The method of detaching according to claim 13, wherein the insulated film is displaced relative to the conductive pad.

15. The method of detaching according to claim 13, wherein the insulated film is displaced relative to the electronic component.

add C2